



8th ESA-ESTEC D/TEC-QCA

Final presentation day

January 24th, 2007

Louvain-la-Neuve

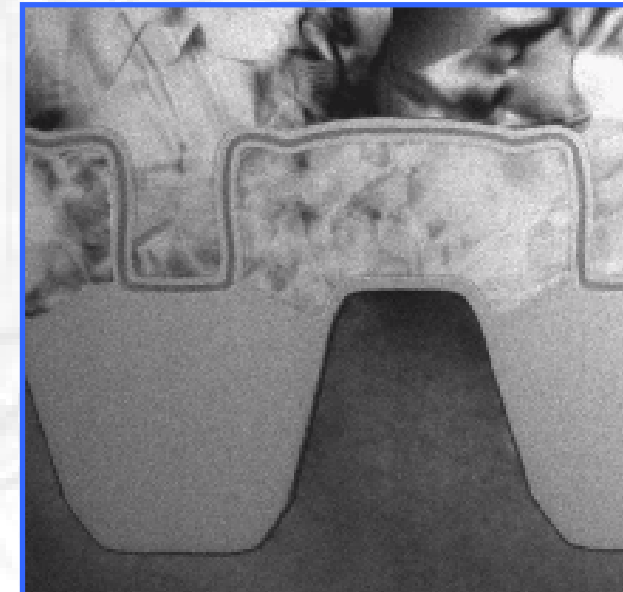
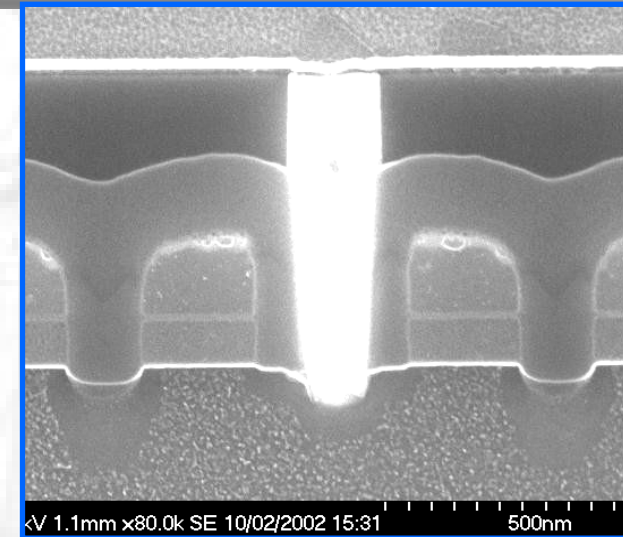
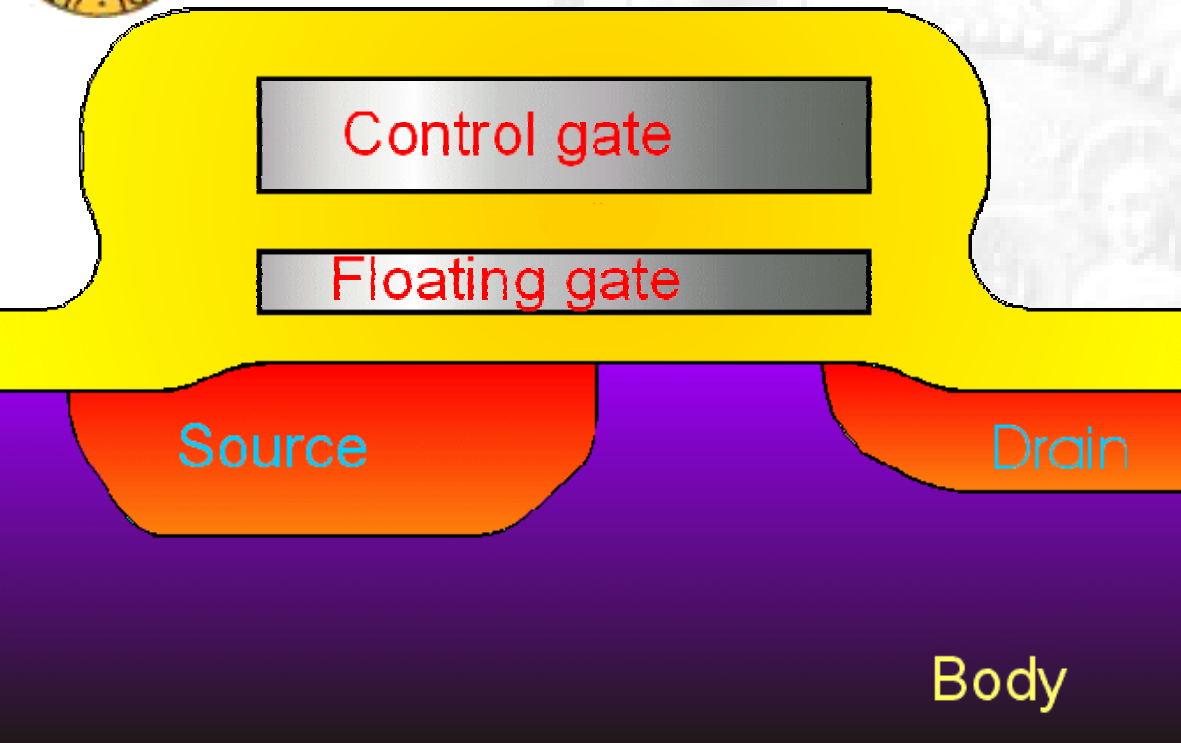
STUDY OF HEAVY ION RADIATION EFFECTS IN FLASH MEMORIES

TEC-QCA Support Activity

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- V_{TH} of the device is controlled by controlling the number of electrons/holes stored in the FG



- Introduction
- Single event effect: prompt charge loss from a Floating Gate cell
- RILC and FG retention issues
- Space distribution of hit FG cells
- Recent results at RADEF (Jyvaskyla)



● Technology nodes

- 0.25 μm
- 0.18 μm
- 0.15 μm
- 0.13 μm
- 90nm
- 65nm

● Architectures

- NOR
- NAND

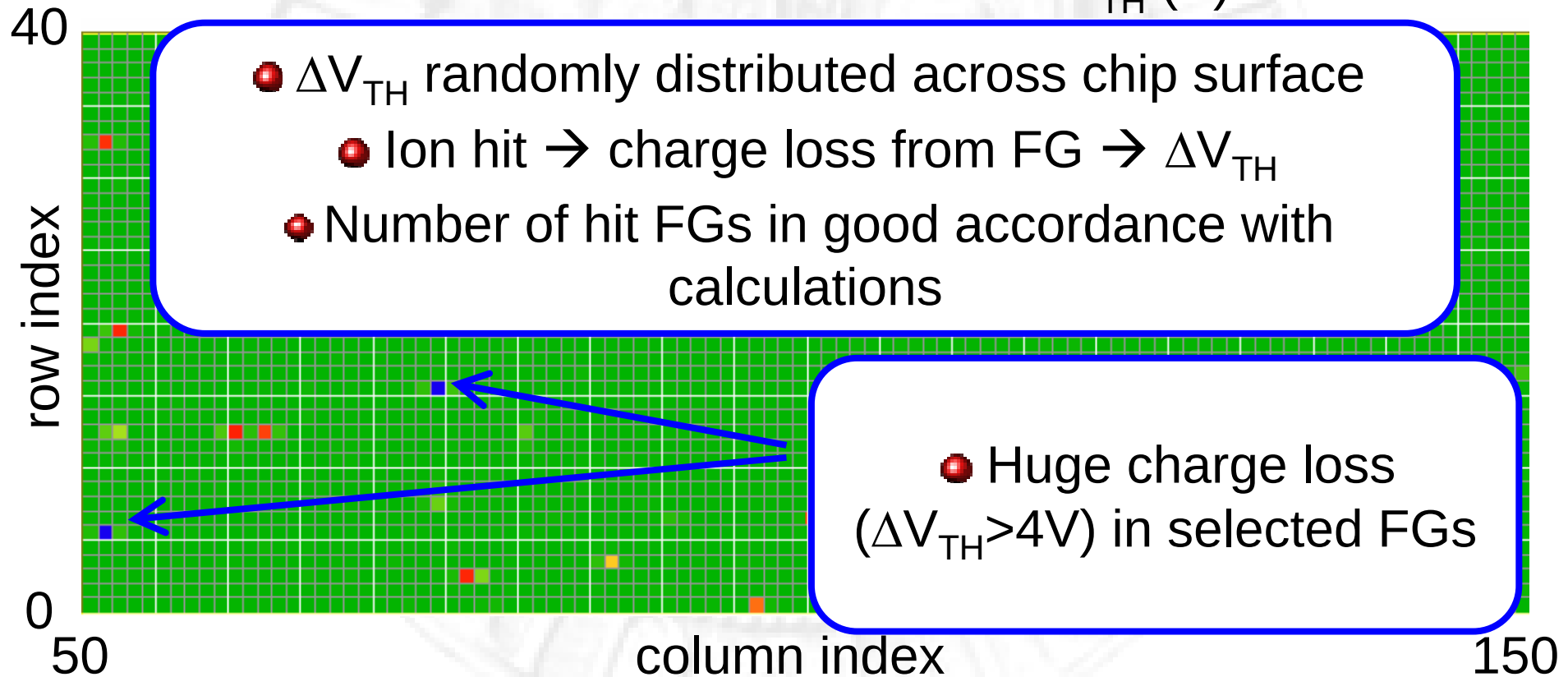
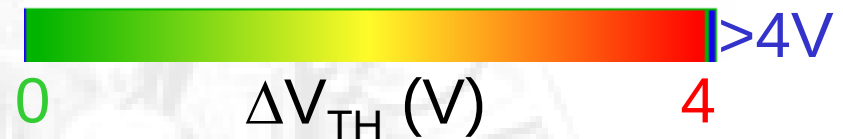
● Test chips and/or reserved algorithms





- 10^7 iodine ions/cm² (LET~64MeVcm²/mg)

- Each square is a FG

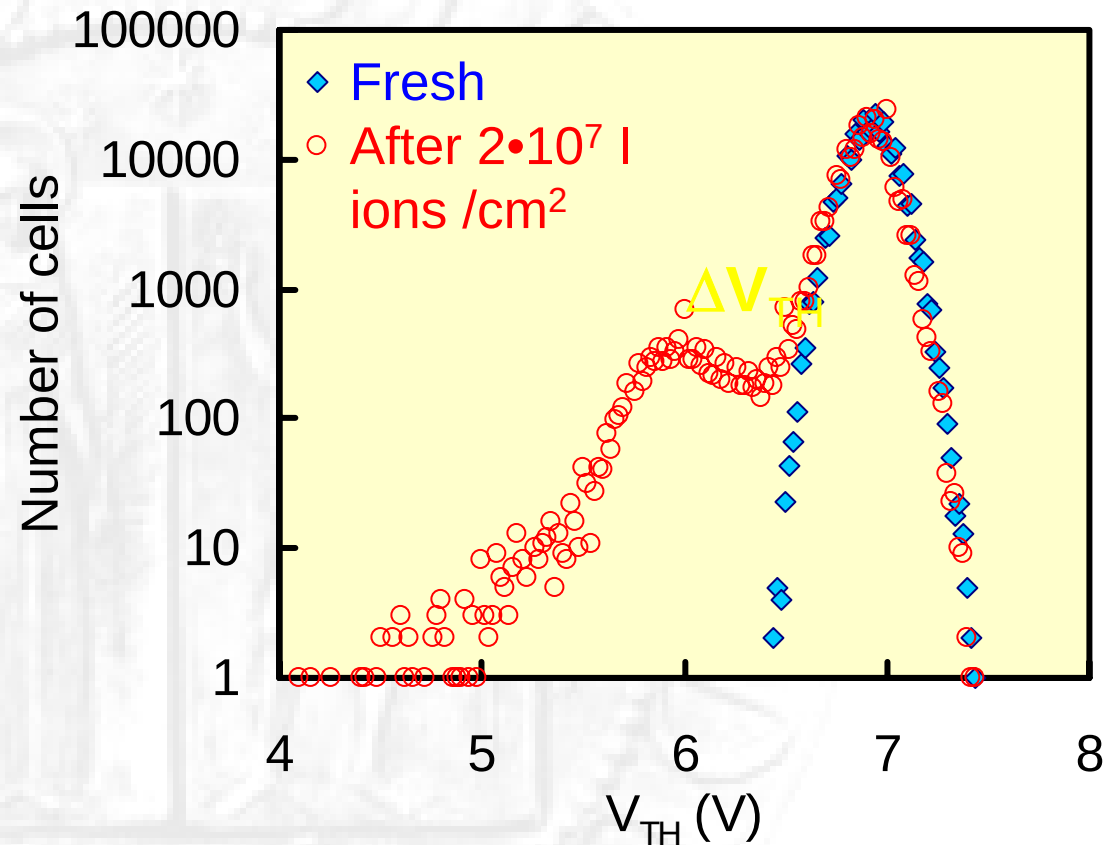




SINGLE EVENT EFFECT: PROMPT CHARGE LOSS FROM A FLOATING GATE CELL



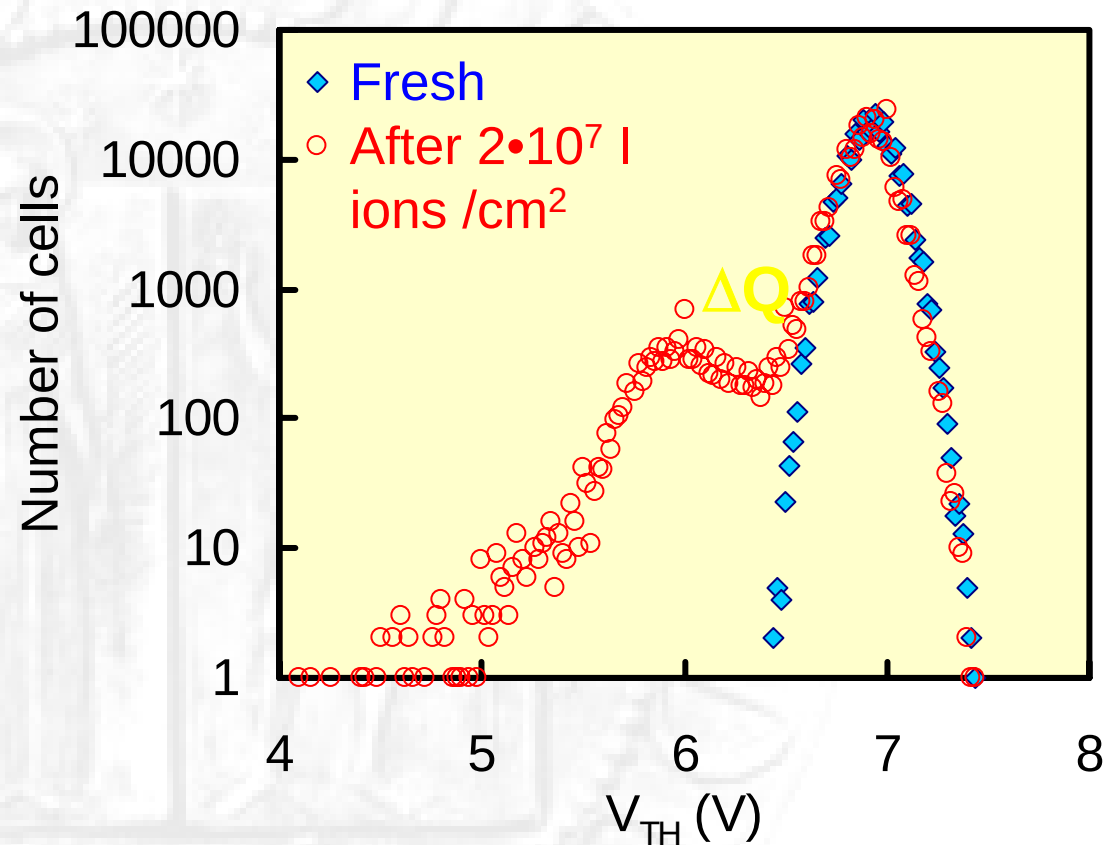
- 0.18 μm technology
- FG cells hit by a single ion form a secondary peak at $\sim 6\text{V}$
- Distance between the peaks = average ΔV_{TH}



FGs in the secondary peak $\leftrightarrow$ ion hit



- How much charge is lost from FG?
- About 7,000 electron/hole pairs are generated
- Less than 1% survive recombination according to the classical models → 70 electrons injected in the FG

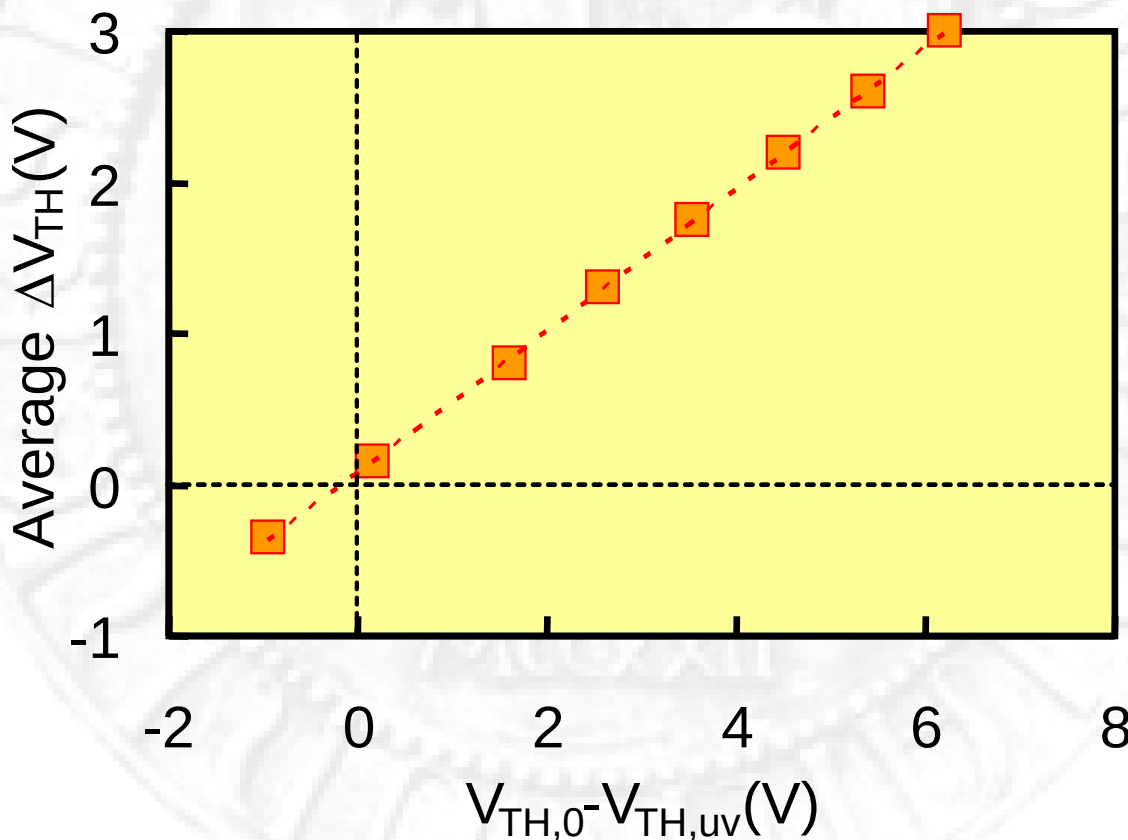


$\Delta Q = 3,500$ electrons



How can we explain charge loss?

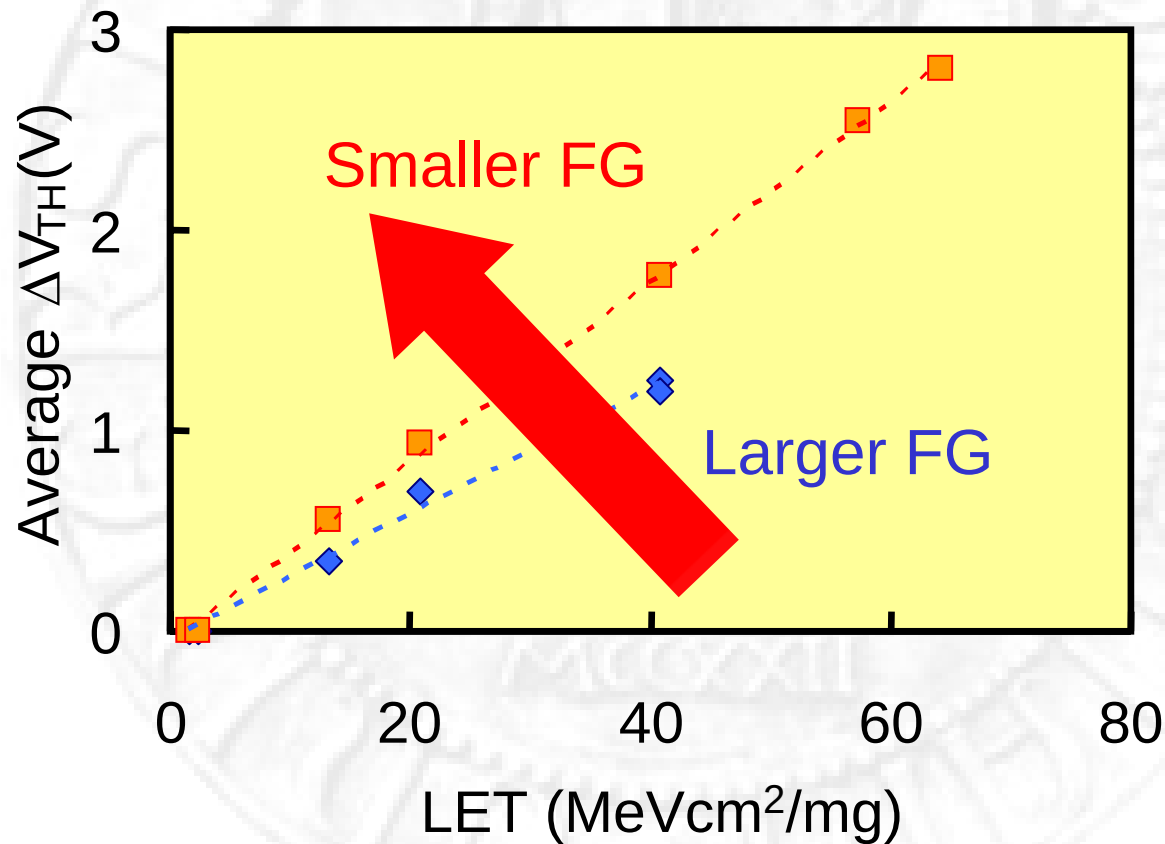
- Average charge loss linearly depends on electric field across the tunnel oxide before irradiation...





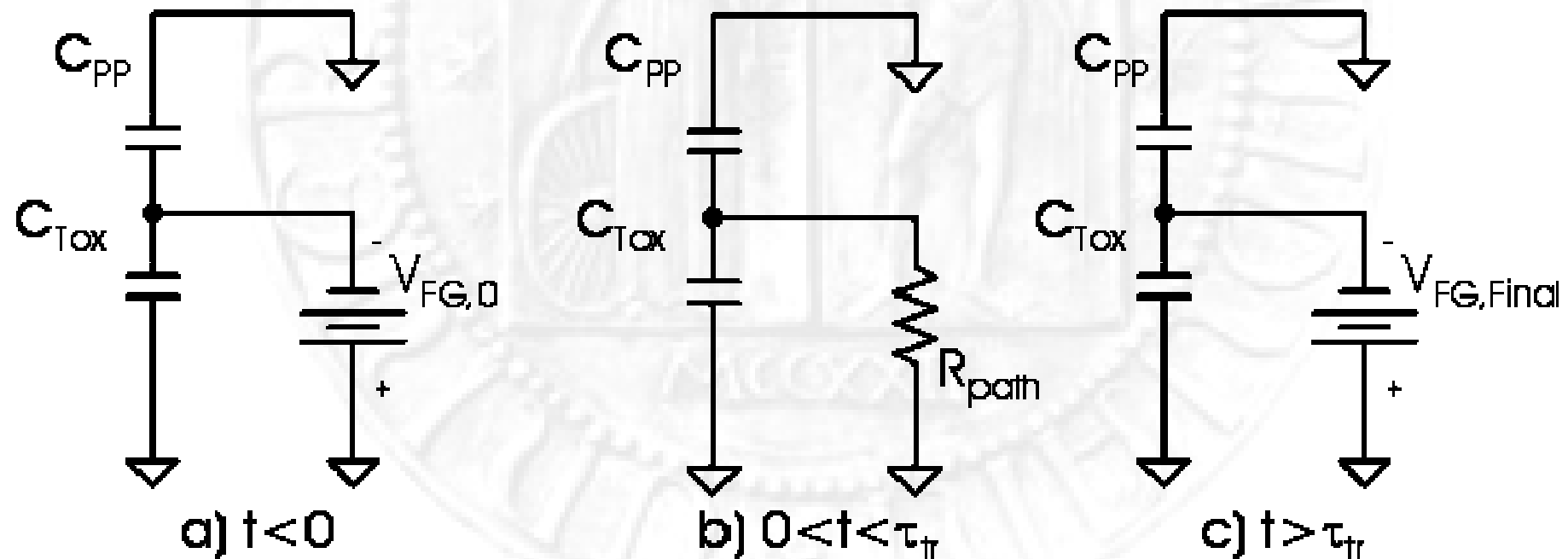
How can we explain charge loss? - 2

- ...it also linearly depends on ion LET!





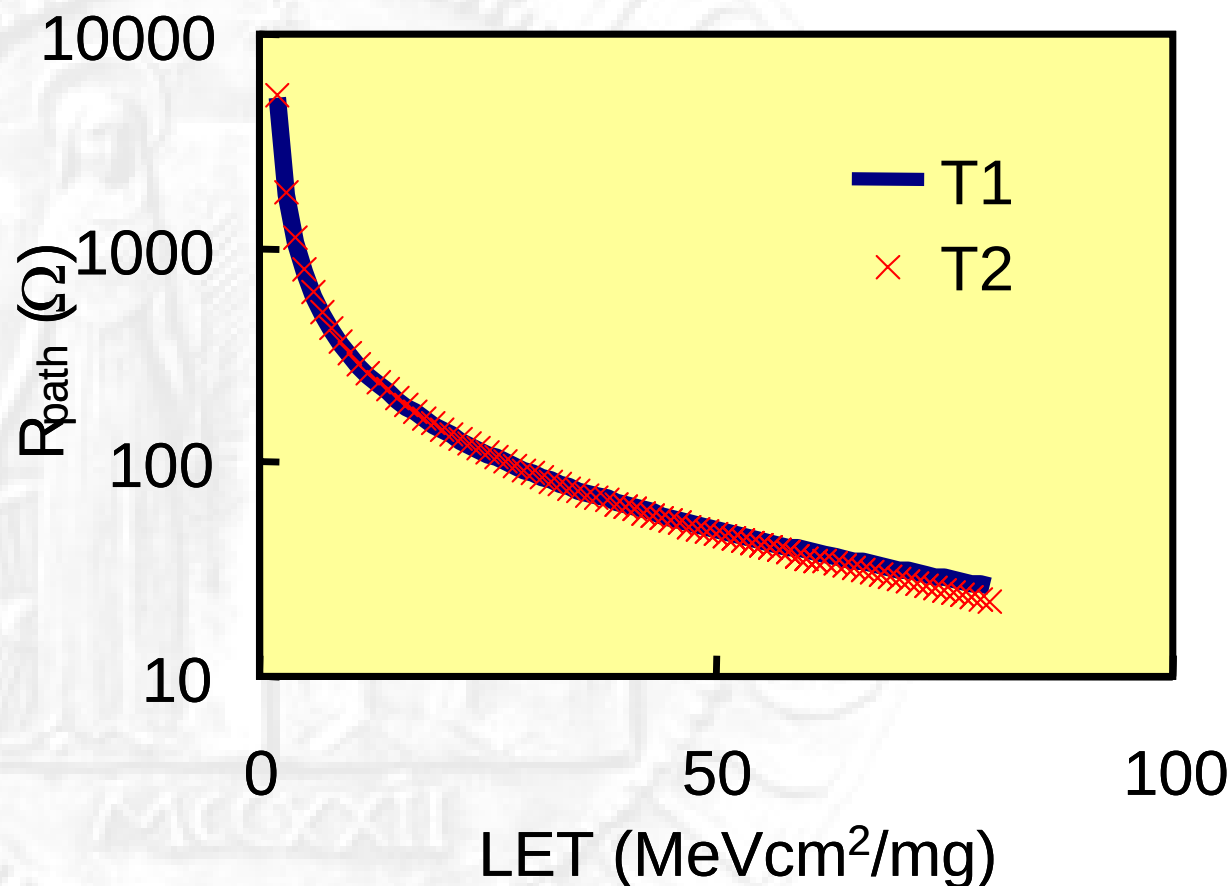
- The e^-/h^+ plasma acts as a resistance, which discharges the FG
- The discharge duration is linked to electron permanence in the oxide: about 10^{-14} seconds (!)





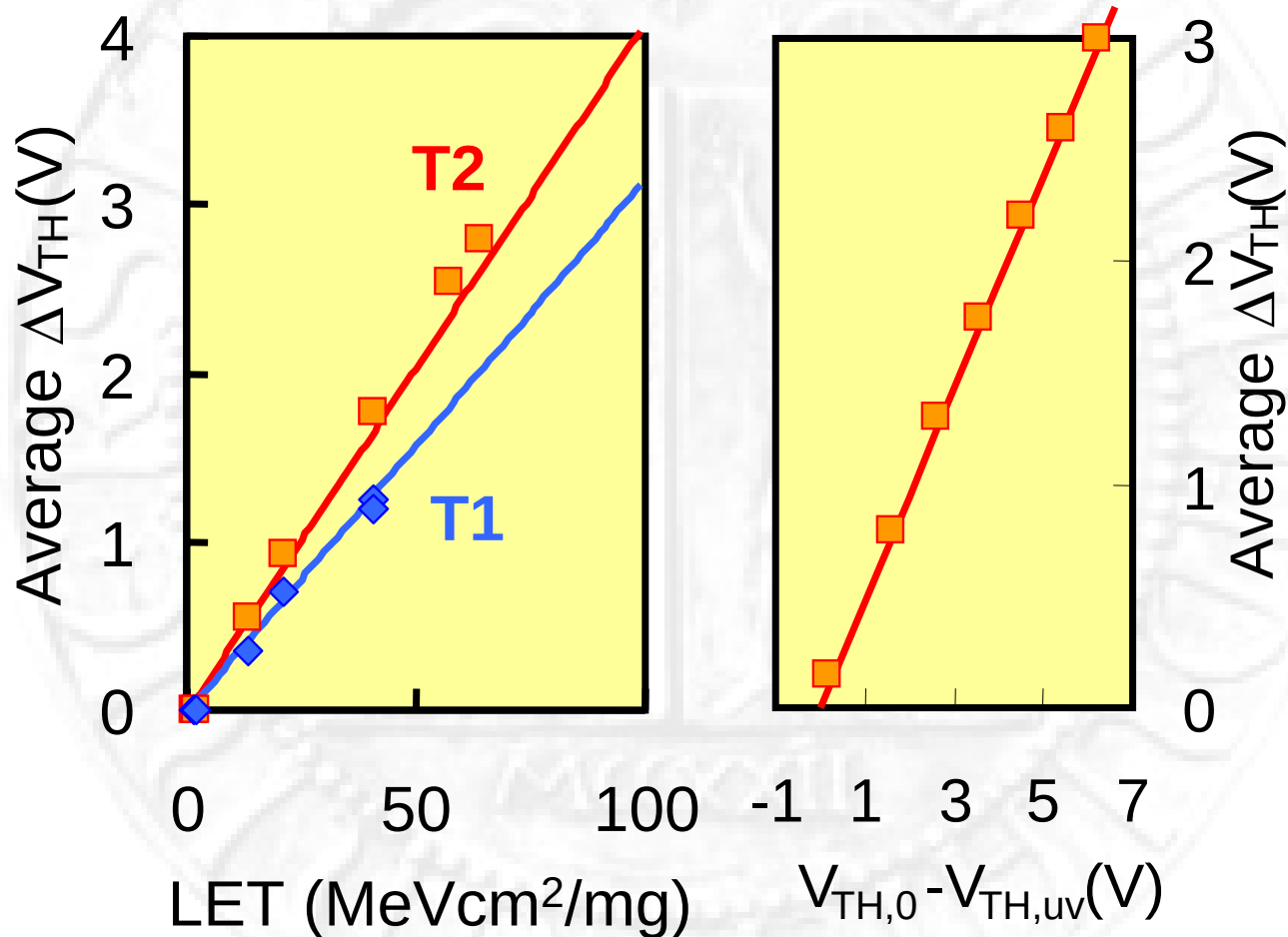
● Values of path resistance obtained for different technologies

- Same resistance $\rightarrow$ path characteristics should not depend on the technology
- In agreement with the high carrier density





● Excellent fitting capabilities!



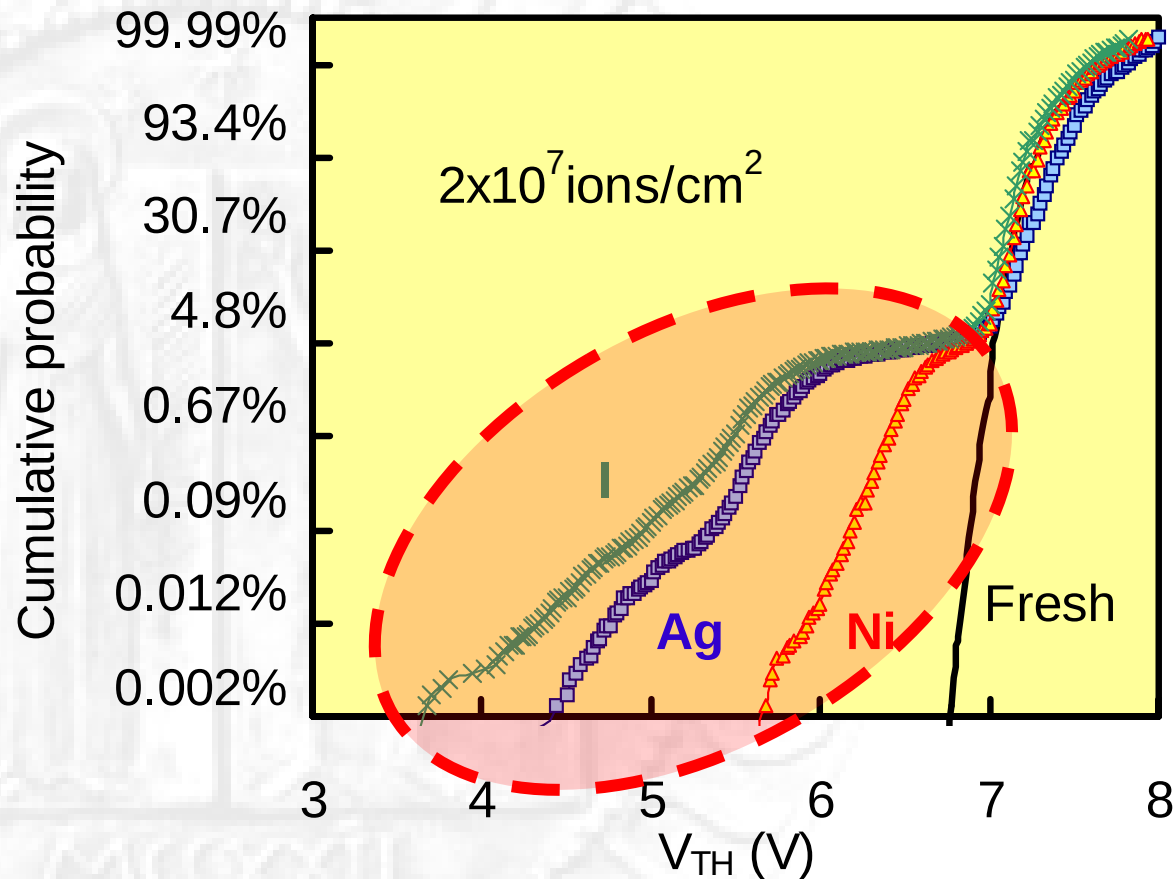


RILC AND FG RETENTION ISSUES



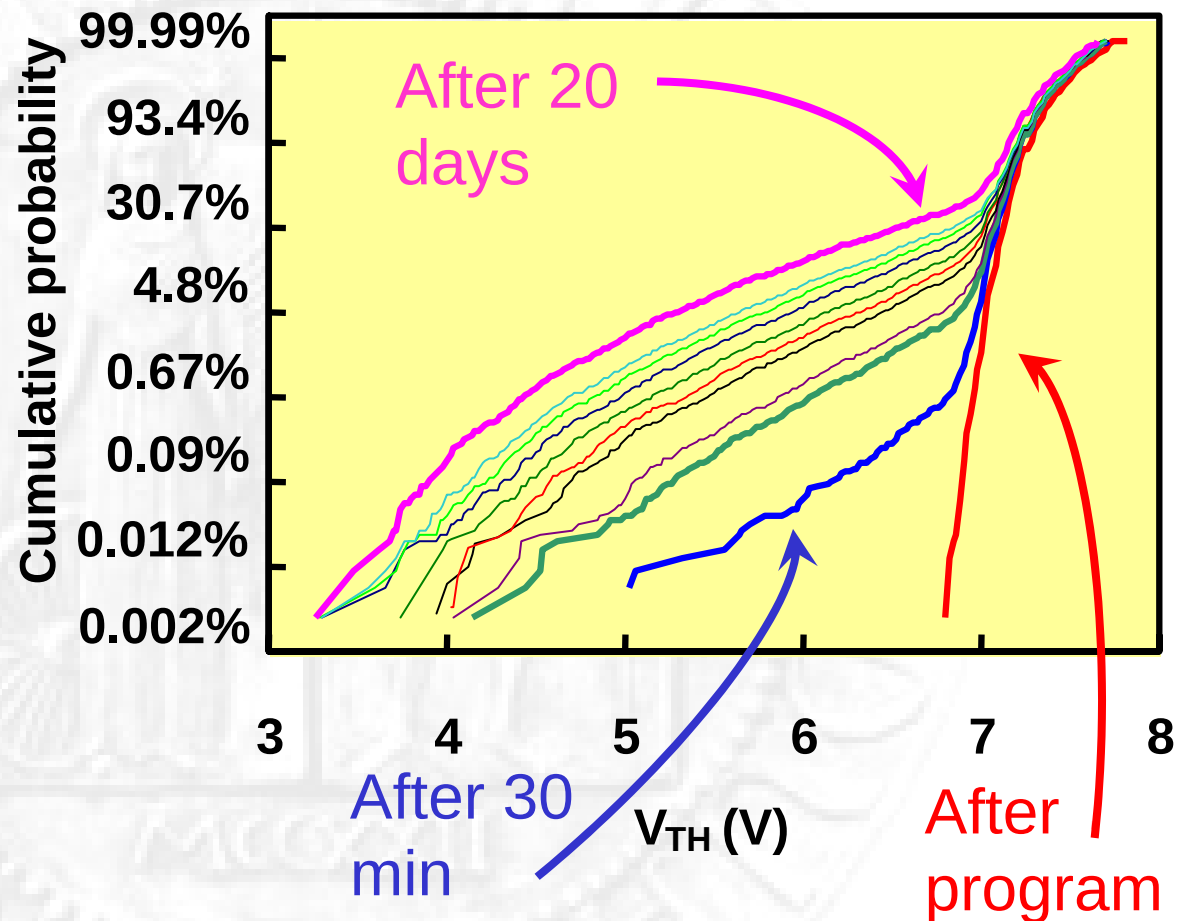
Radiation Effects on V_{TH} distributions

- Large tails after heavy ions irradiation
- Number of bits in tail does not depend on ion LET (it depends on fluence)
- ΔV_{TH} strongly depends on ion LET
- Only hit cells are considered in next experiments





- Only hit FGs were programmed
- After only 30min a clear tail appears...
- ...which increases more and more with time



After 20 days, $\Delta V_{TH} \sim 4V!!!$



What's going on?

- Ion generates a plasma of electrons and holes

Tunnel Oxide

Floating gate
(electrons stored)

Ion track

• holes

• electrons

Substrate

[1] Cellere, et al., IEEE T-NS, 2002

[2] Larcher, et al., IEEE T-NS, 2002



What's going on?

- Ion generates a plasma of electrons and holes
- Prompt columnar recombination

Tunnel Oxide

Floating gate
(electrons stored)

holes
electrons

Substrate

- [1] Cellere, et al., IEEE T-NS, 2002
- [2] Larcher, et al., IEEE T-NS, 2002

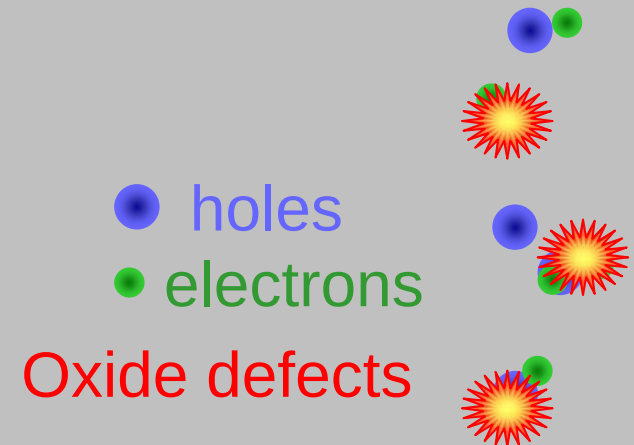


What's going on?

- Ion generates a plasma of electrons and holes
- Prompt columnar recombination
- Followed/accompanied by generation of oxide defects

Tunnel Oxide

Floating gate
(electrons stored)



Substrate

[1] Cellere, et al., IEEE T-NS, 2002

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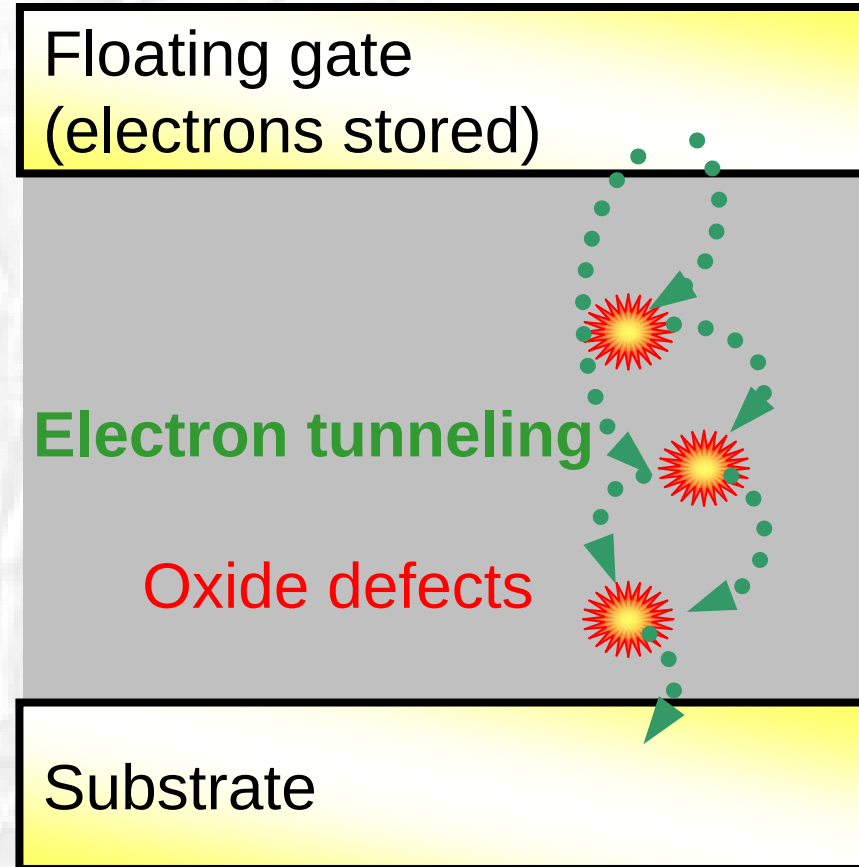
What's going on?

- Ion generates a plasma of electrons and holes
- Prompt columnar recombination
- Followed/accompanied by generation of oxide defects

Oxide defects are used by electrons to escape the FG

- multi-Trap Assisted Tunneling (m-TAT)

Tunnel Oxide



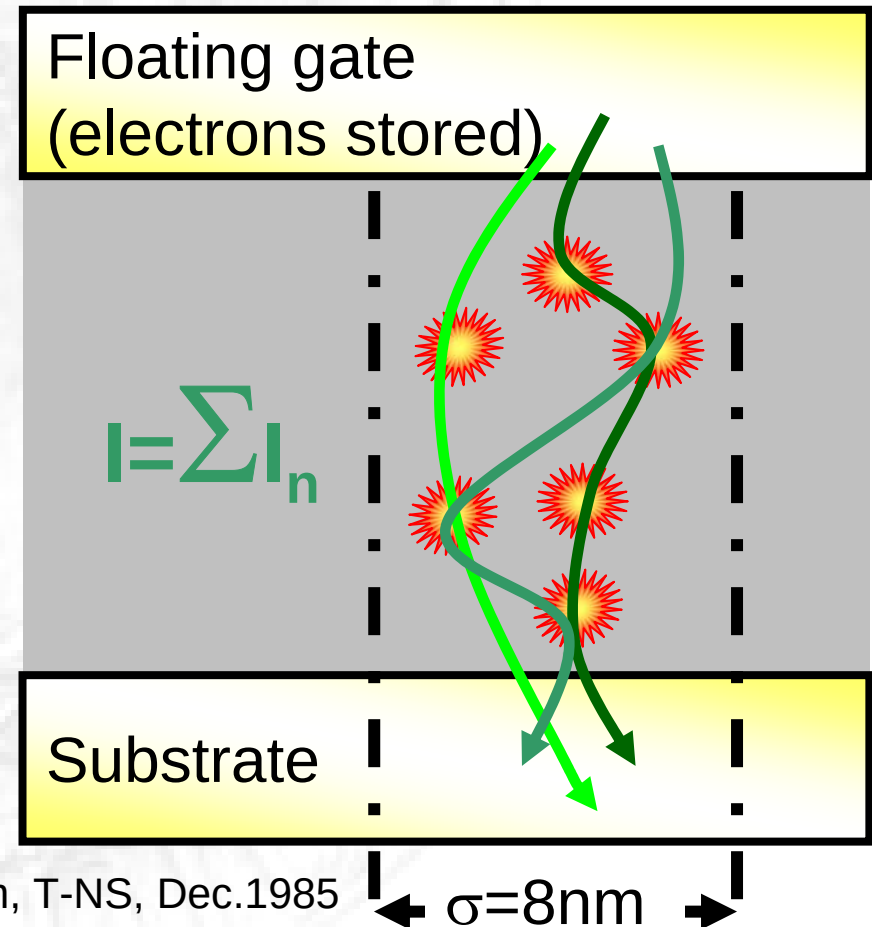
[1] Cellere, et al., IEEE T-NS, 2002

[2] Larcher, et al., IEEE T-NS, 2002



- How can we evaluate the current along this path?
- Consider the ion track [1]
- Randomly generate a Gaussian distribution of defects
- Evaluate the current through each possible path
- Then sum all the currents

Tunnel Oxide



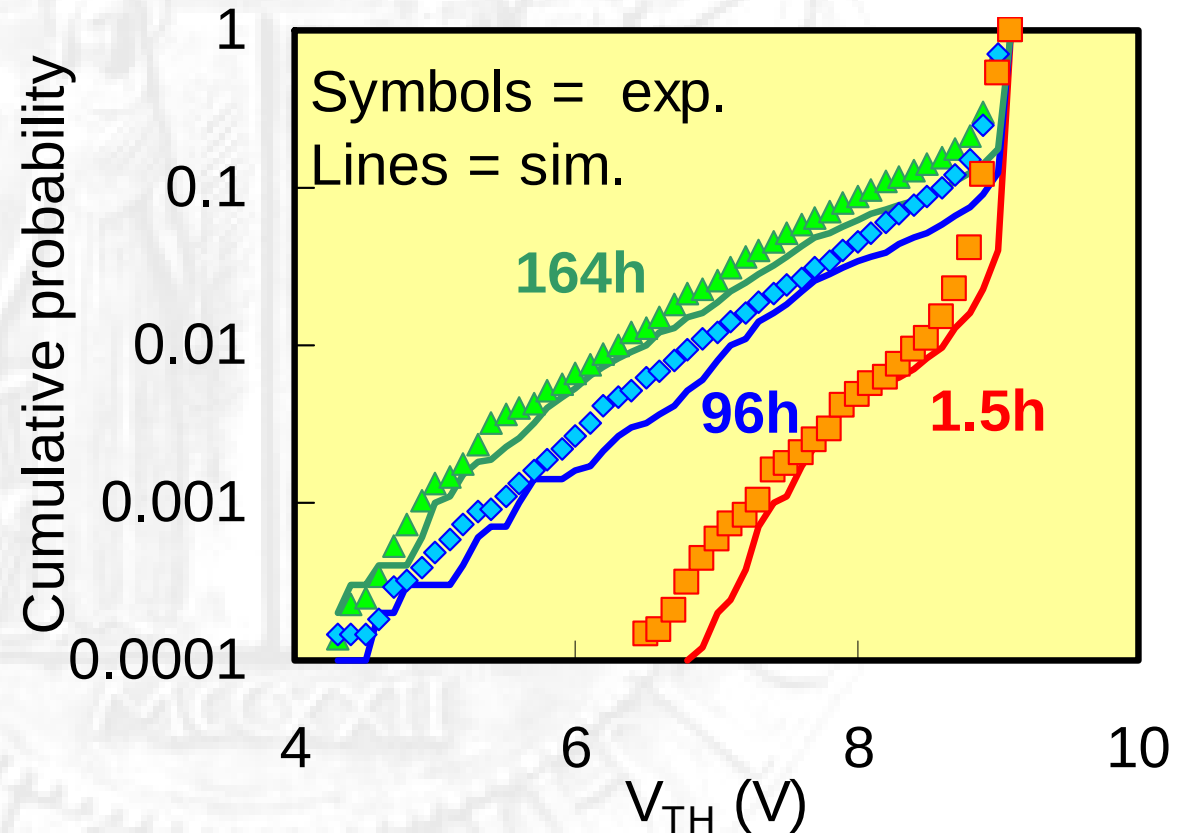
[1] Oldham, T-NS, Dec.1985



- 0.15 μm technology

- After Iodine
(LET=64
 MeVcm^2/mg)
irradiation

- 12 oxide defects



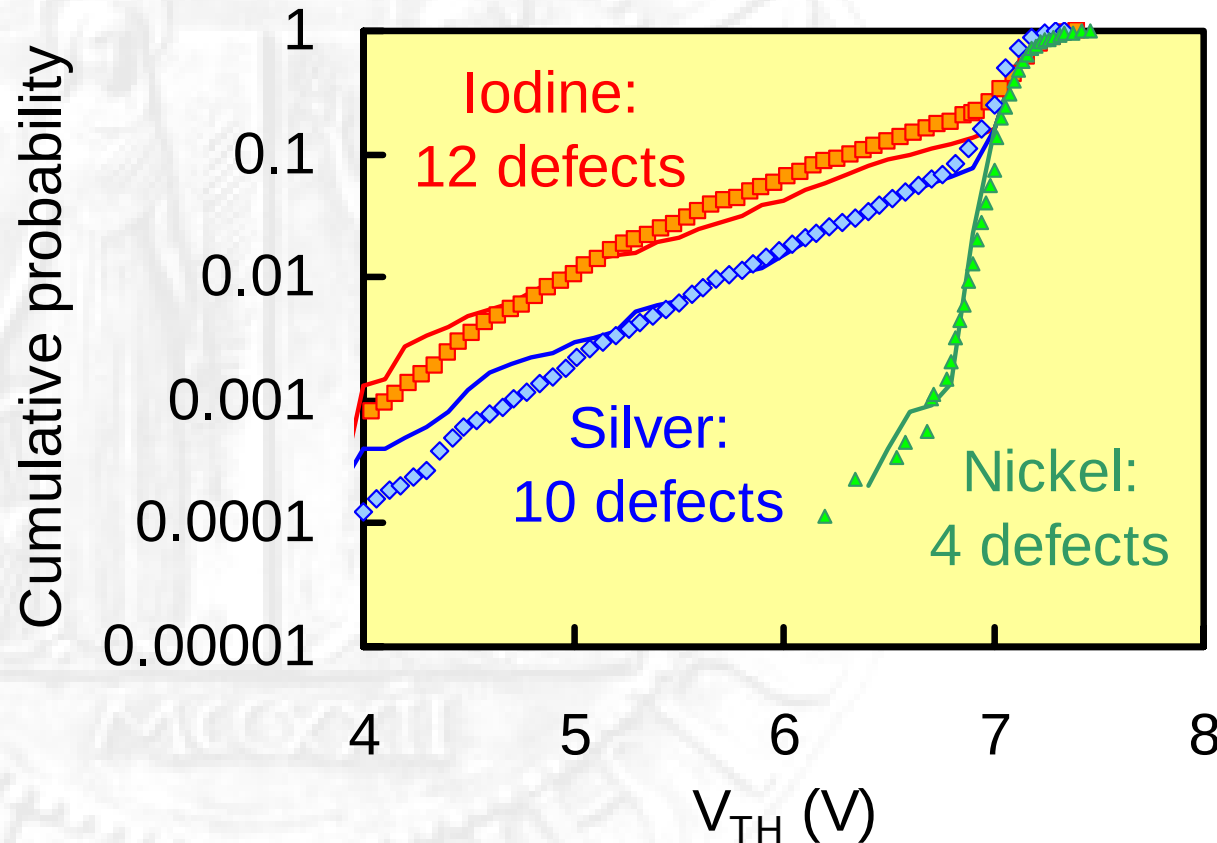


- 0.13 μm technology

- After 529hours

- Different ions $\rightarrow$ change only the number of oxide defects

- Smaller FG $\rightarrow$ larger ΔV_{TH}





Three retention experiments:

- Programming + irradiation

- Reading

- **Experiment 1:**

- Program

- Reading

- **Experiment 2:**

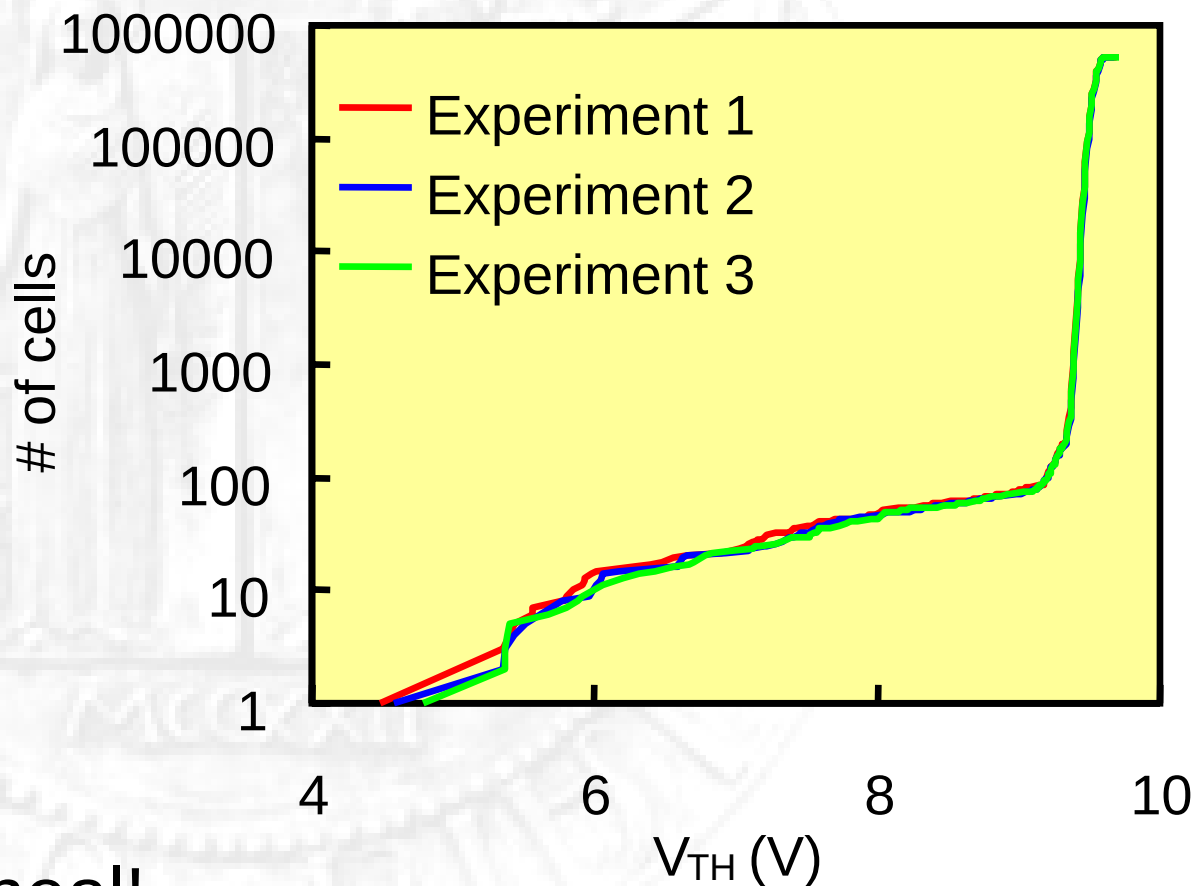
- Program

- Reading

- **Experiment 3:**

- Program

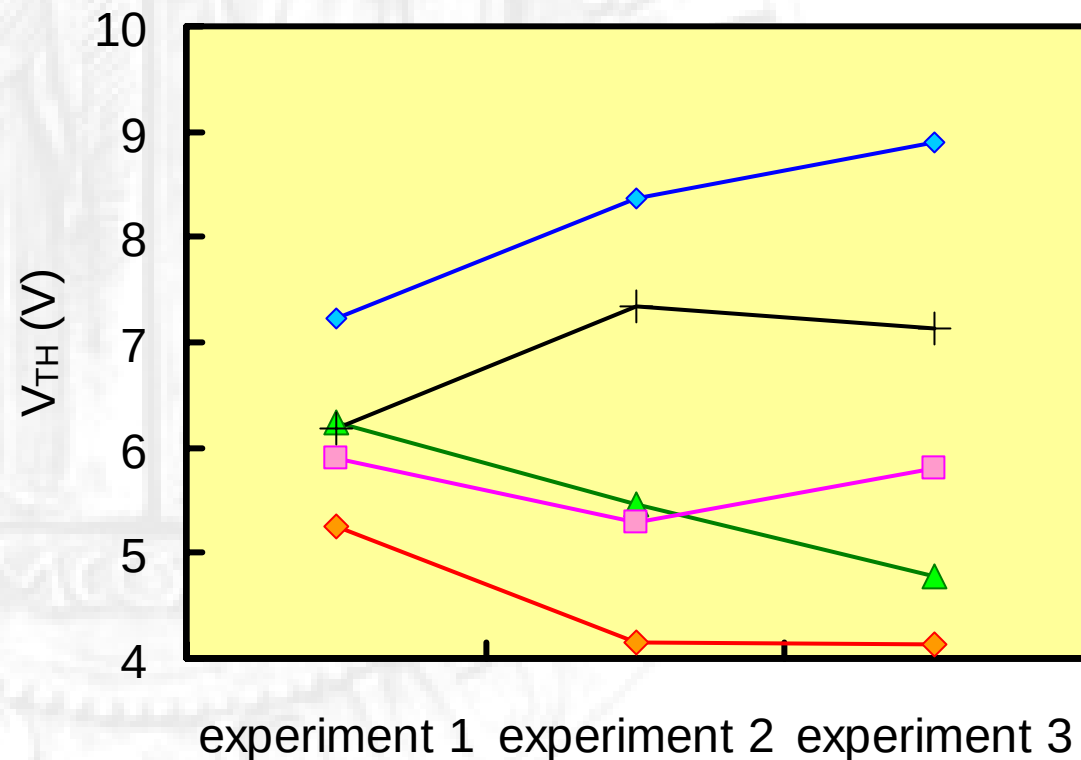
- Reading



RILC does not anneal!



- However, in some FG cells the V_{TH} changes a lot during the three experiments!
- Due to changes of occupancy state of any “critical” defect in the RILC path
- Similar erratic behavior is well known for SILC

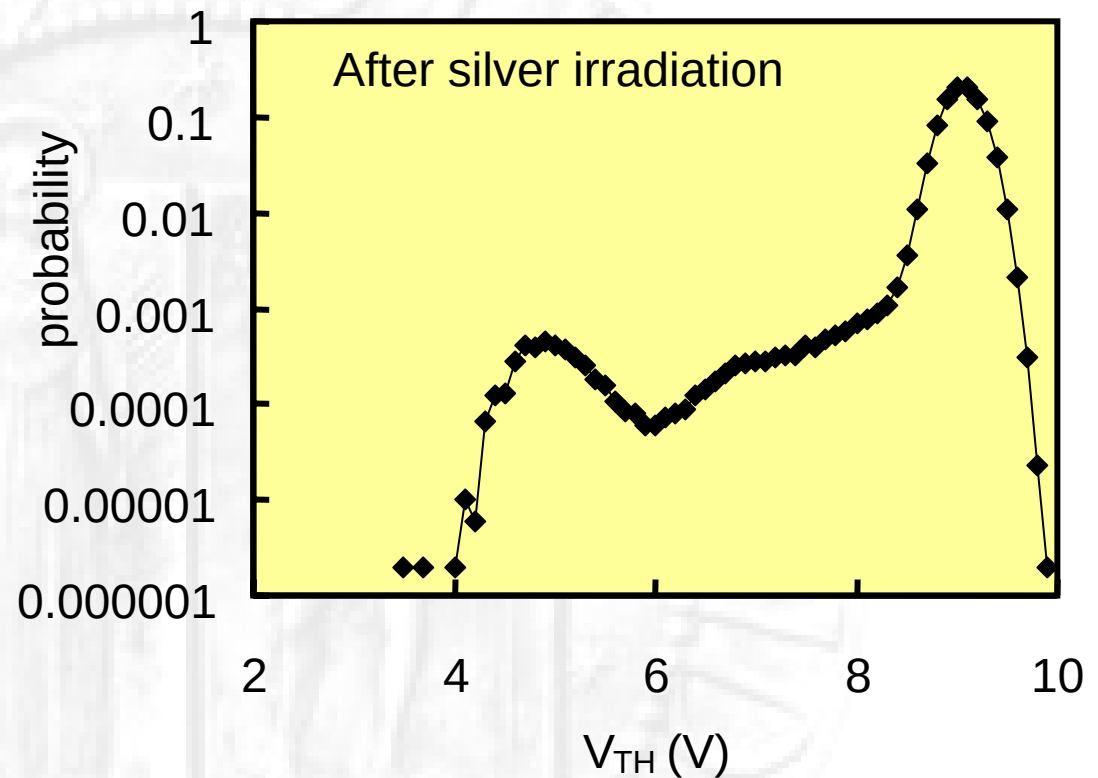




SPACE DISTRIBUTION OF HIT FG CELLS

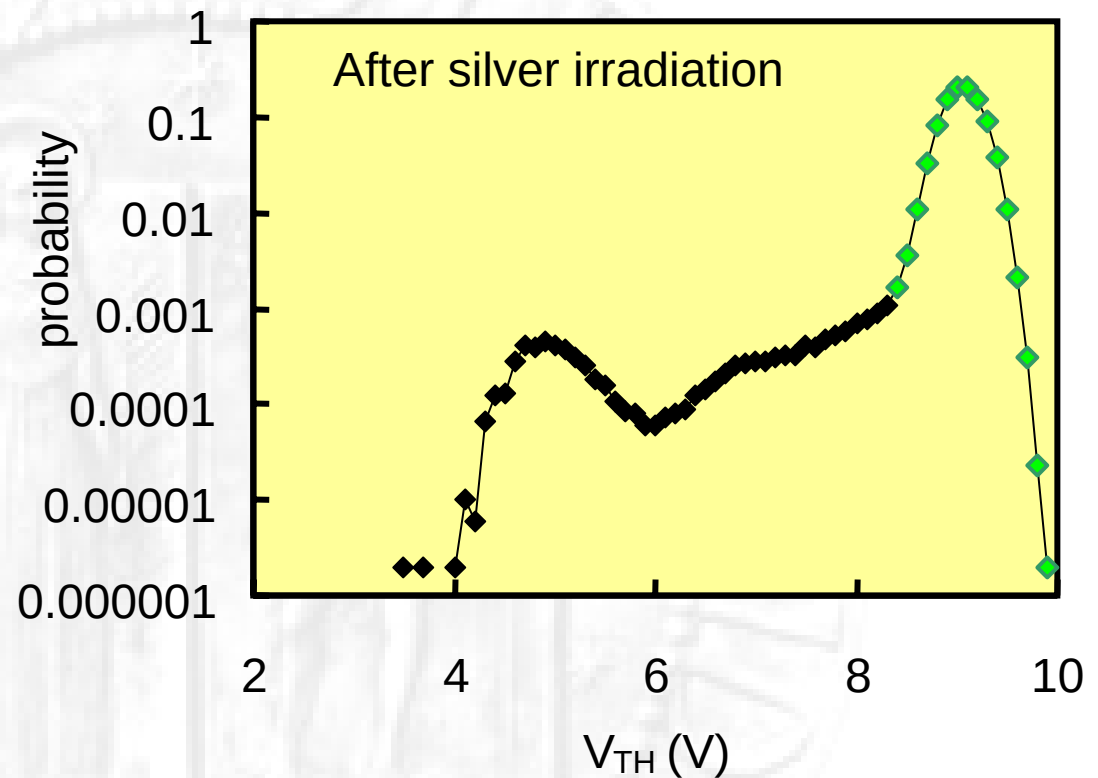


- 90 nm technology
- Three families



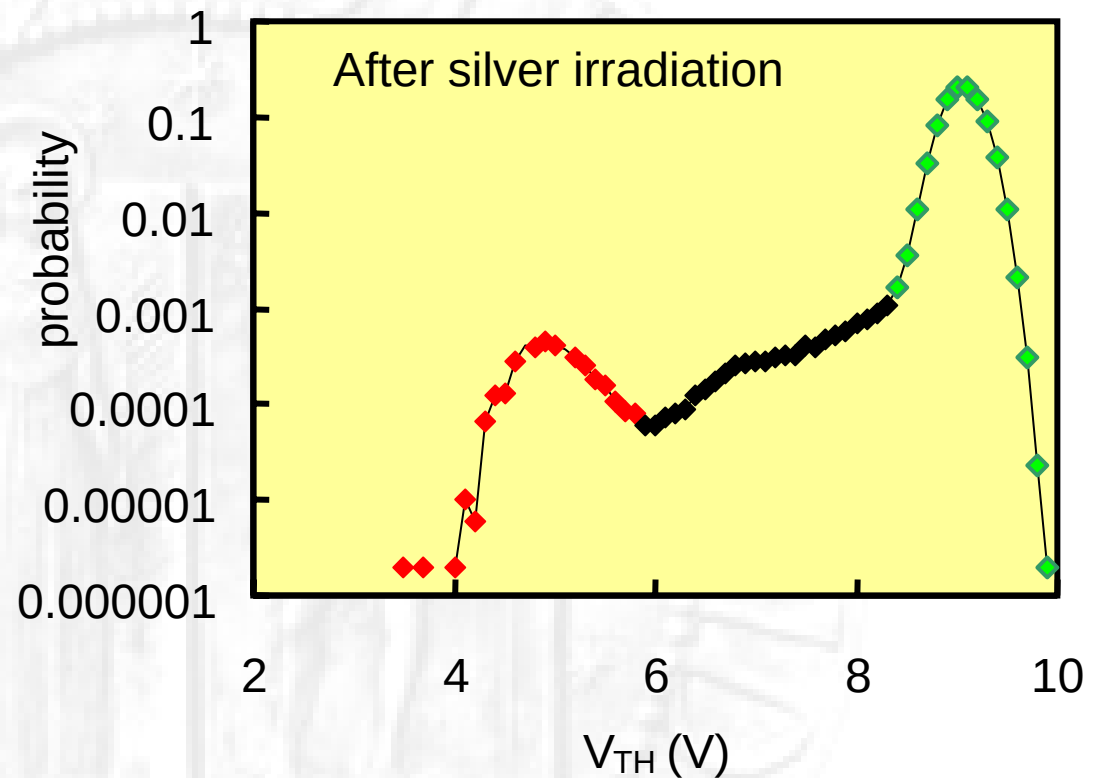


- 90 nm technology
- Three families
- “Green” FGs
 - Main distribution
 - Not hit





- 90 nm technology
- Three families
 - “Green” FGs
 - Main distribution
 - Not hit
 - “Red” FGs
 - Hit by ions
 - Large charge loss





- 90 nm technology

- Three families

- “Green” FGs

- Main distribution

- Not hit

- “Red” FGs

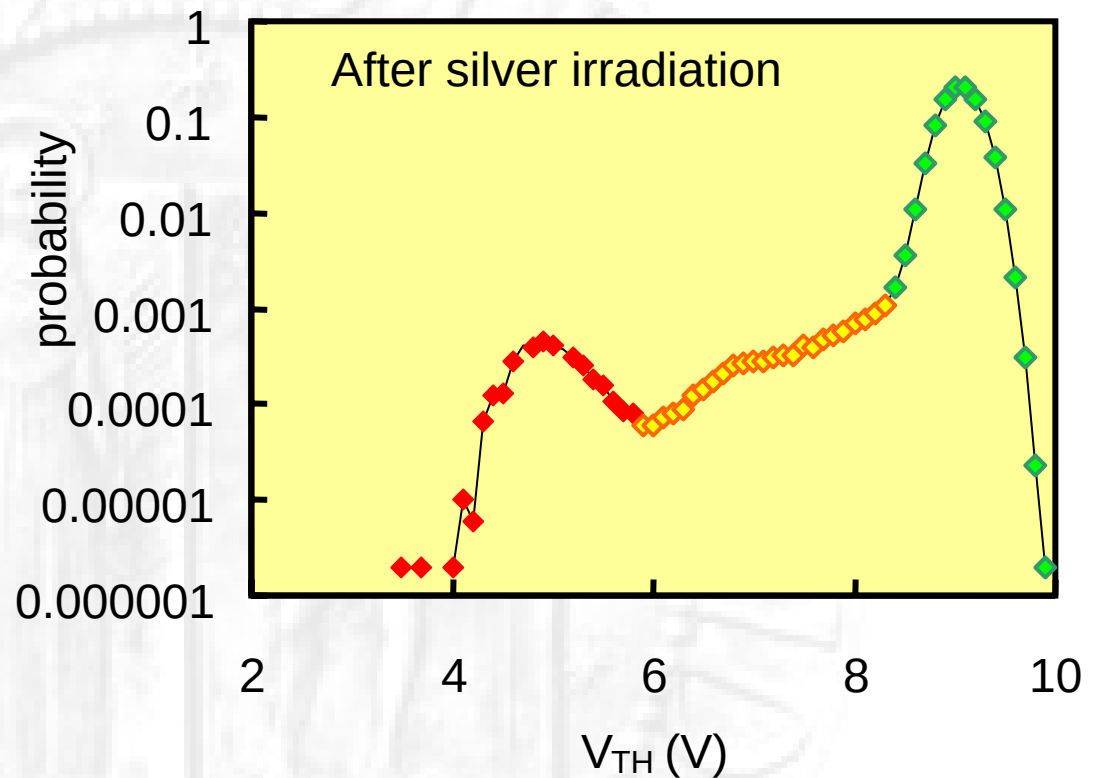
- Hit by ions

- Large charge loss

- “Yellow” FGs

- Not hit

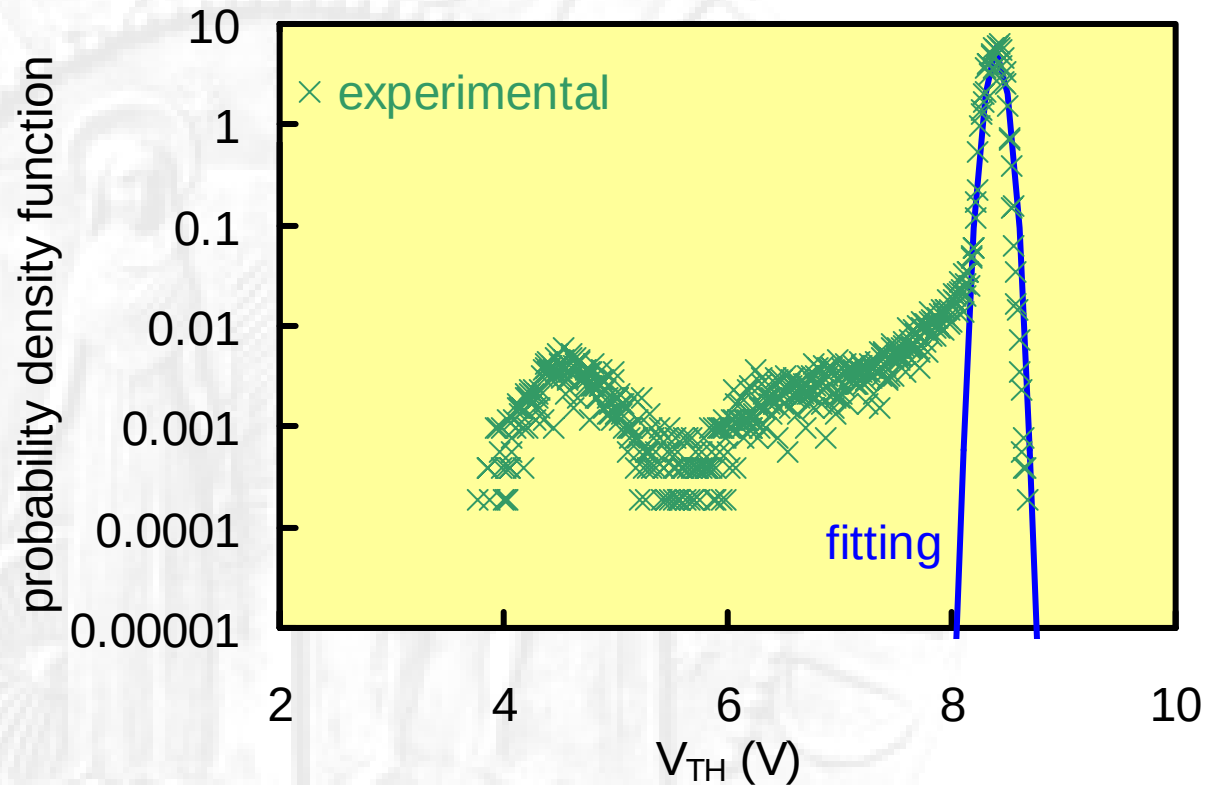
- $\Delta V_{TH} > 0$



Corruption of the stored information can happen even in FGs not directly hit by ions!

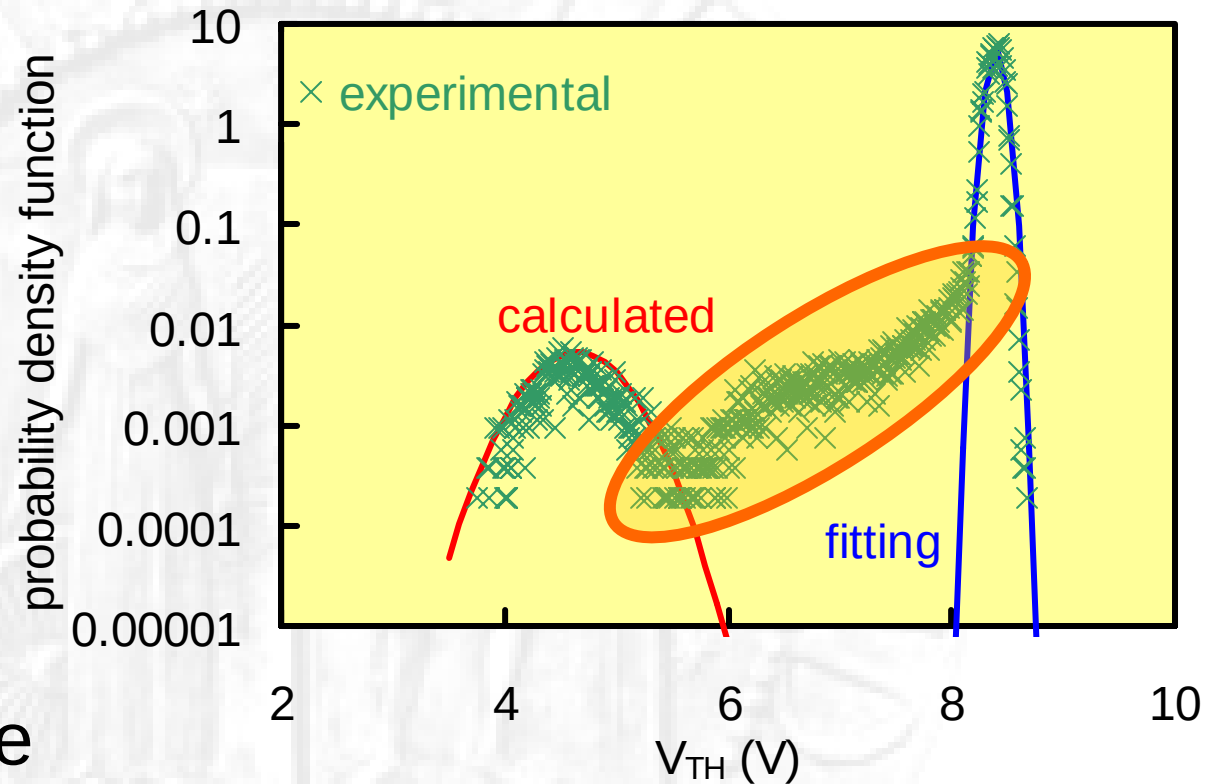


- The main peak can be approximated by a Gaussian





- The main peak can be approximated by a Gaussian
- Based on
 - $V_{TH,pre-rad}$
 - ΔV_{TH}
- One can calculate the distribution of the secondary peak

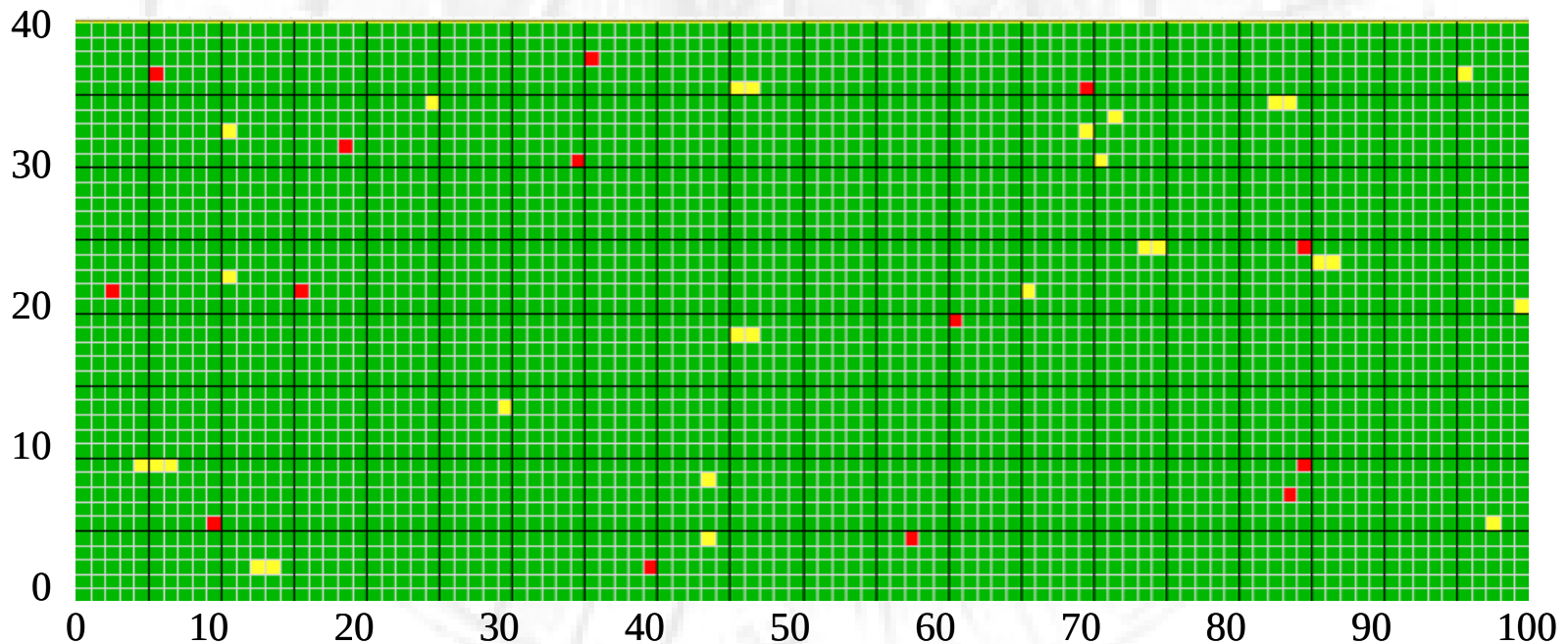


- “Red” FGs: very good fitting
- What about “yellow” cells?



Yellow and red FGs are randomly distributed on chip surface, but:

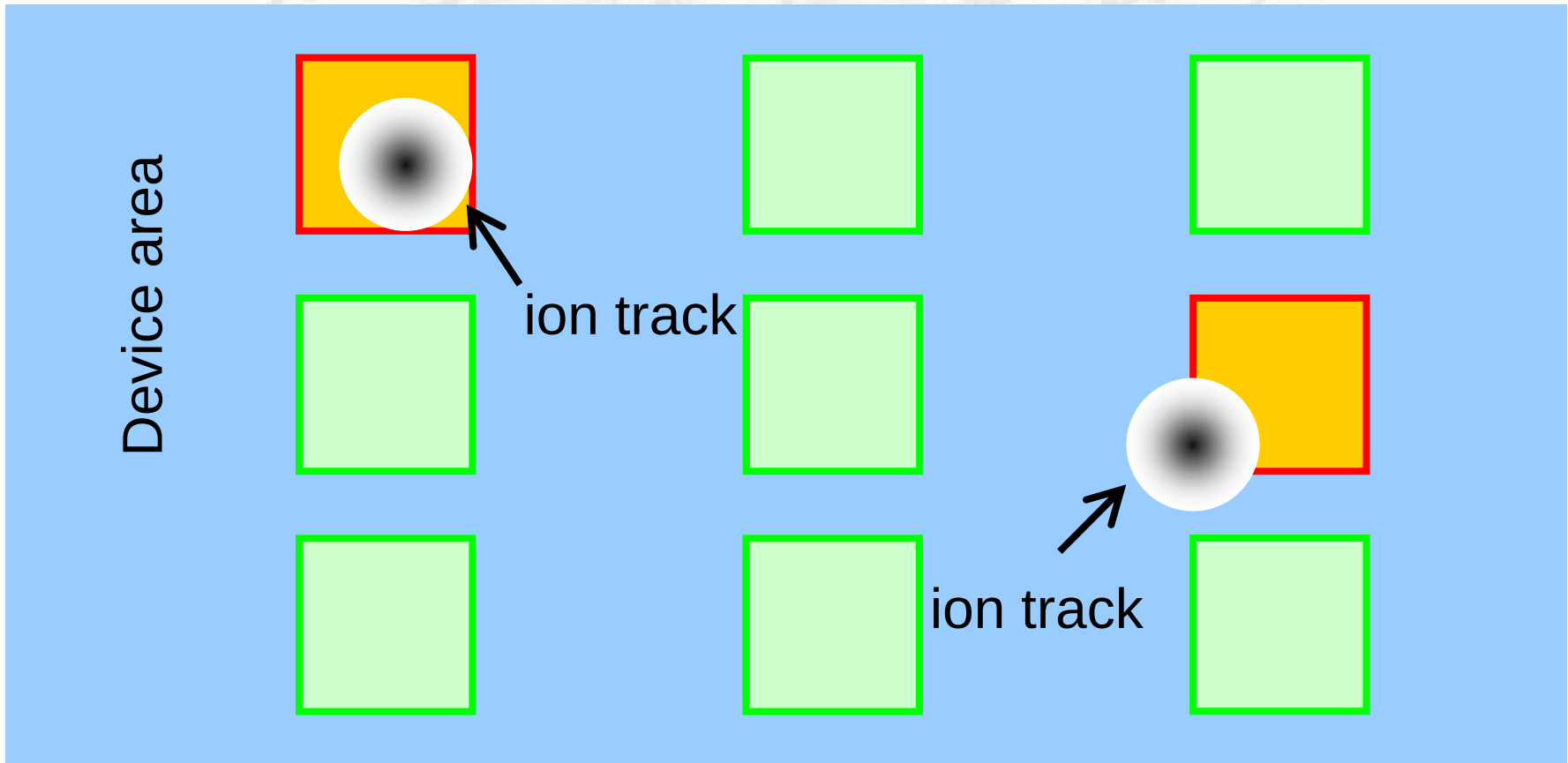
- Almost all red FGs are isolated
- 30% of yellow FGs are clustered





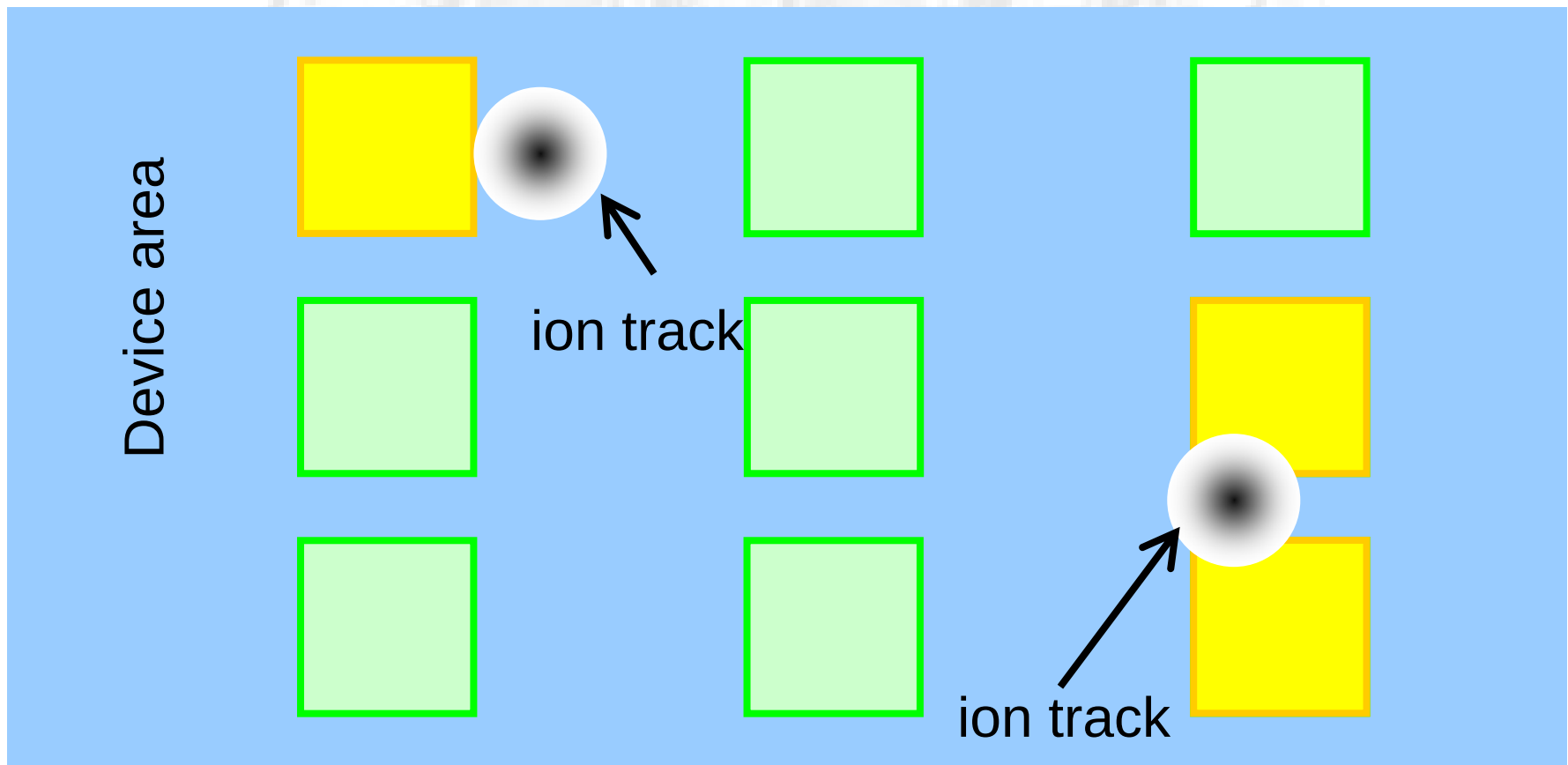


Ion crossing the FG $\rightarrow$ RED





Ion crossing “close” to the FG → YELLOW





RECENT RESULTS AT RADEF (JYVASKYLA)

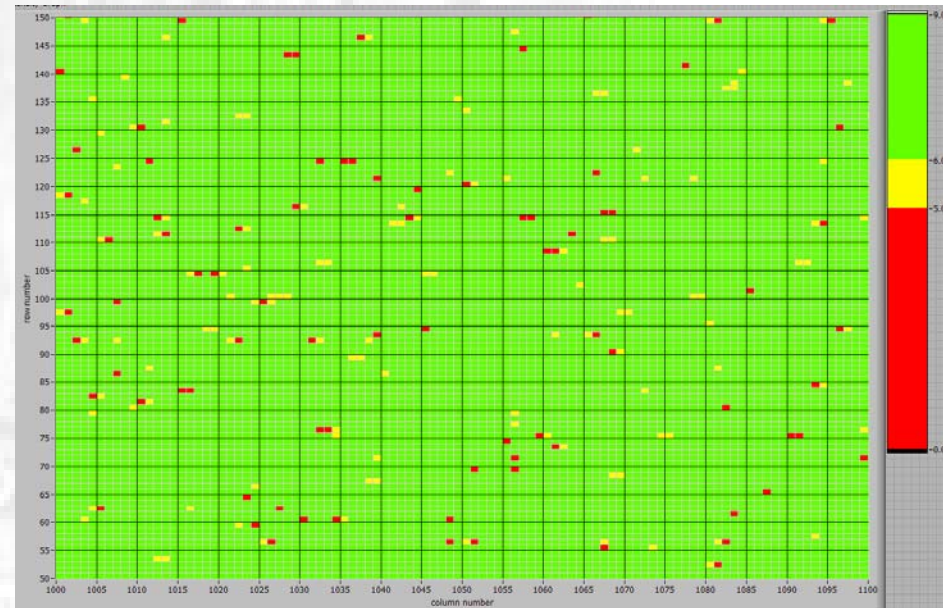


First experiments have been conducted at RADEF-Jyvaskyla in Dec 2006 thanks to ESA-ESTEC support (RHS) to study this phenomenon vs.:

- Incidence angle
- Ion energy



1217MeV Xe



768MeV Kr



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